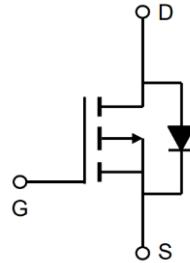


-30V P-Channel Enhancement Mode MOSFET

Description

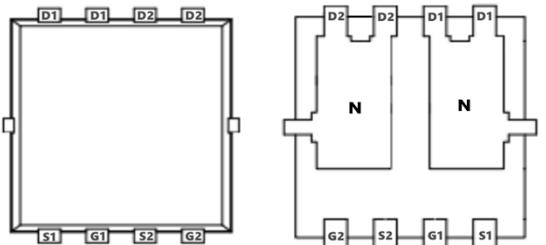
The HN60P03DF uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.



General Features

$V_{DS} = -30V$ $I_D = -60A$

$R_{DS(ON)} < 8m\Omega$ @ $V_{GS} = -10V$

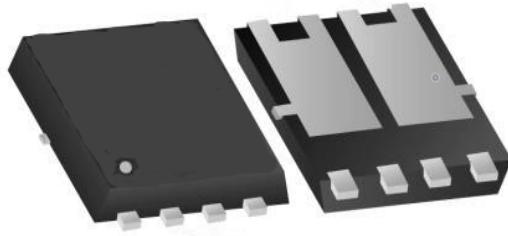


Application

Lithium battery protection

Wireless impact

Mobile phone fast charging



Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
HN60P03DF	PDFN3*3-8L	HN60P03DF XXX YYYY	5000

Absolute Maximum Ratings ($TC=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	-30	V
V_{GS}	Gate-Source Voltage	± 20	V
$I_D @ T_c = 25^\circ C$	Continuous Drain Current, $V_{GS} @ -10V^1$	-60	A
$I_D @ T_c = 100^\circ C$	Continuous Drain Current, $V_{GS} @ -10V^1$	-32	A
I_{DM}	Pulsed Drain Current ²	-200	A
EAS	Single Pulse Avalanche Energy ³	125	mJ
I_{AS}	Avalanche Current	-50	A
$P_D @ T_c = 25^\circ C$	Total Power Dissipation ⁴	38	W
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ C$
T_J	Operating Junction Temperature Range	-55 to 150	$^\circ C$
$R_{\theta JA}$	Thermal Resistance Junction-Ambient ¹	65	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance Junction-Case ¹	3.3	$^\circ C/W$



-30V P-Channel Enhancement Mode MOSFET
Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BVDSS	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$, $I_D=-250\mu\text{A}$	-30	-32	---	V
RDS(ON)	Static Drain-Source On-Resistance ²	$V_{GS}=-10\text{V}$, $I_D=-10\text{A}$	---	6.8	8.0	$\text{m}\Omega$
		$V_{GS}=-4.5\text{V}$, $I_D=-8\text{A}$	---	9.3	13	
VGS(th)	Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_D=-250\mu\text{A}$	-1.2	-1.6	-2.5	V
IDSS	Drain-Source Leakage Current	$V_{DS}=-24\text{V}$, $V_{GS}=0\text{V}$, $T_J=25^\circ\text{C}$	---	---	-1	uA
		$V_{DS}=-24\text{V}$, $V_{GS}=0\text{V}$, $T_J=55^\circ\text{C}$	---	---	-5	
IGSS	Gate-Source Leakage Current	$V_{GS}=\pm 20\text{V}$, $V_{DS}=0\text{V}$	---	---	± 100	nA
gfs	Forward Transconductance	$V_{DS}=-5\text{V}$, $I_D=-20\text{A}$	---	25	---	S
Qg	Total Gate Charge (-4.5V)	$V_{DS}=-15\text{V}$, $V_{GS}=-4.5\text{V}$, $I_D=-15\text{A}$	---	30	---	nC
Qgs	Gate-Source Charge		---	10	---	
Qgd	Gate-Drain Charge		---	10.4	---	
Td(on)	Turn-On Delay Time	$V_{DD}=-15\text{V}$, $V_{GS}=-10\text{V}$, $R_G=3.3\Omega$ $I_D=-15\text{A}$	---	9.4	---	ns
T _r	Rise Time		---	10.2	---	
Td(off)	Turn-Off Delay Time		---	117	---	
T _f	Fall Time		---	24	---	
Ciss	Input Capacitance	$V_{DS}=-15\text{V}$, $V_{GS}=0\text{V}$, $f=1\text{MHz}$	---	3448	---	pF
Coss	Output Capacitance		---	508	---	
Crss	Reverse Transfer Capacitance		---	421	---	
IS	Continuous Source Current ^{1,5}	$V_G=V_D=0\text{V}$, Force Current	---	---	-50	A
ISM	Pulsed Source Current ²		---	---	-130	A
VSD	Diode Forward Voltage ²	$V_{GS}=0\text{V}$, $I_S=-1\text{A}$, $T_J=25^\circ\text{C}$	---	---	-1	V
trr	Reverse Recovery Time	$IF=-15\text{A}$, $dI/dt=100\text{A}/\mu\text{s}$, $T_J=25^\circ\text{C}$	---	20	---	nS
Qrr	Reverse Recovery Charge		---	9.5	---	nC

Note :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is $V_{DD}=-25\text{V}$, $V_{GS}=-10\text{V}$, $L=0.1\text{mH}$, $I_{AS}=-50\text{A}$
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as I_D , in real applications , should be limited by total power dissipation.

-30V P-Channel Enhancement Mode MOSFET

Typical Characteristics

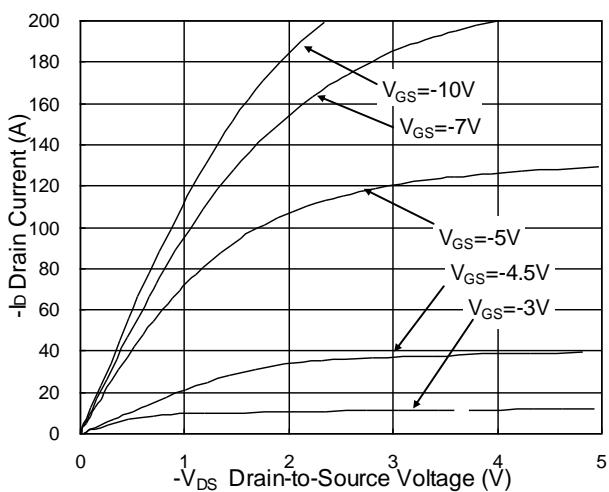


Fig.1 Typical Output Characteristics

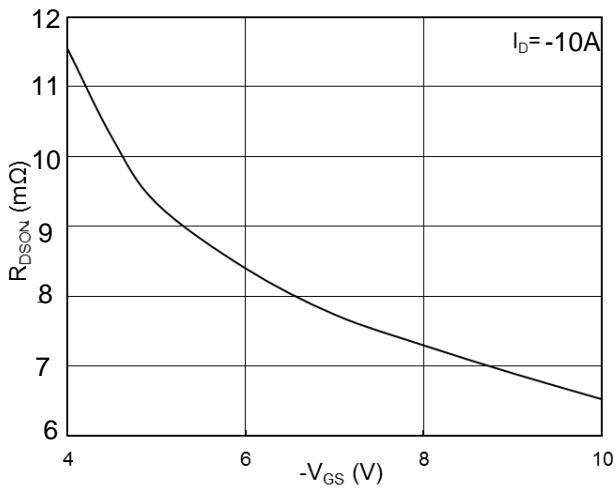


Fig.2 On-Resistance v.s Gate-Source

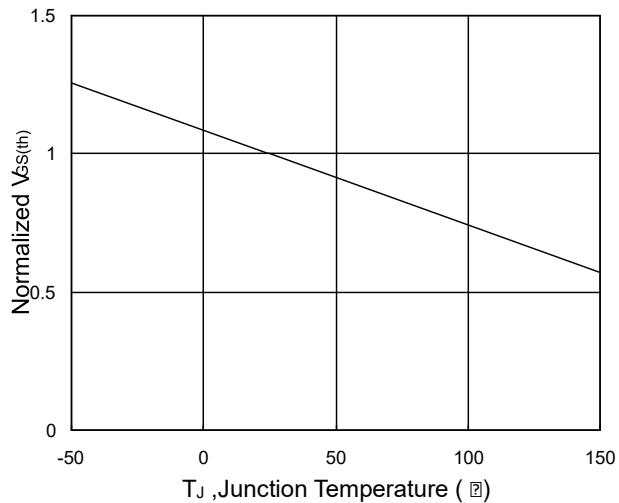
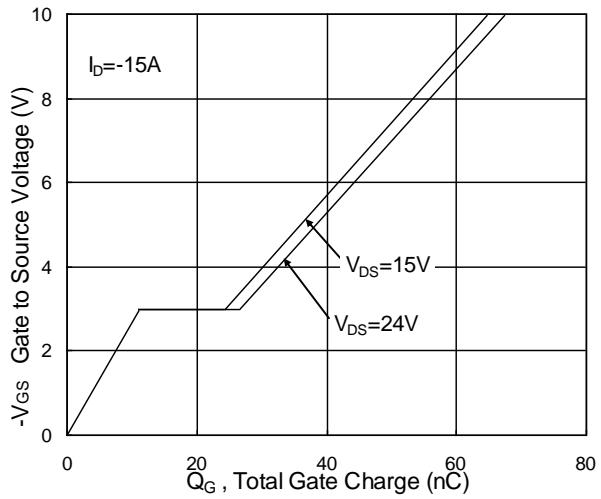
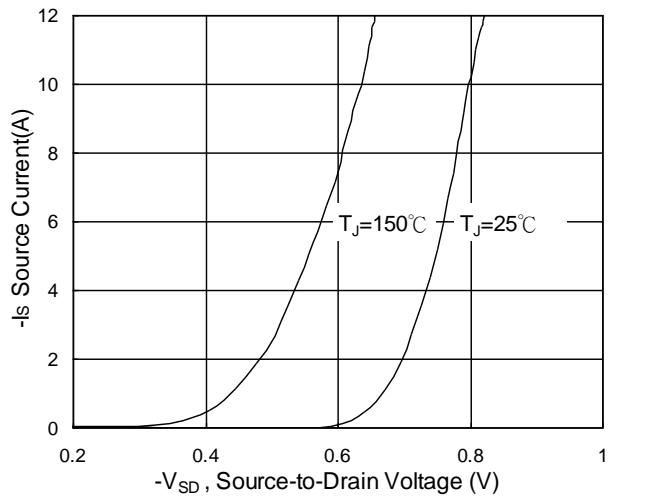


Fig.5 Normalized $V_{GS(th)}$ v.s T_J

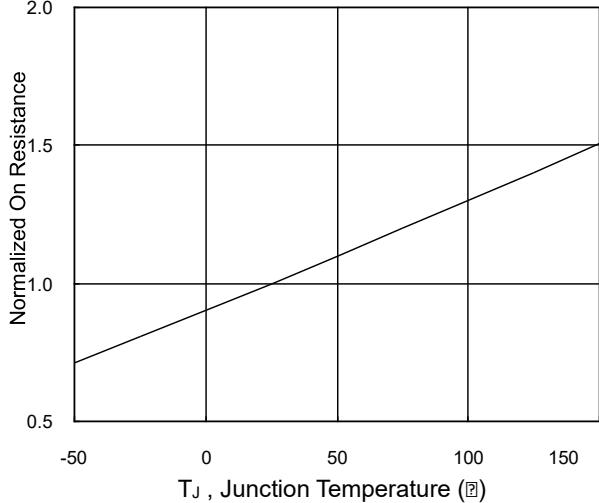


Fig.6 Normalized $R_{DS(on)}$ v.s T_J



-30V P-Channel Enhancement Mode MOSFET

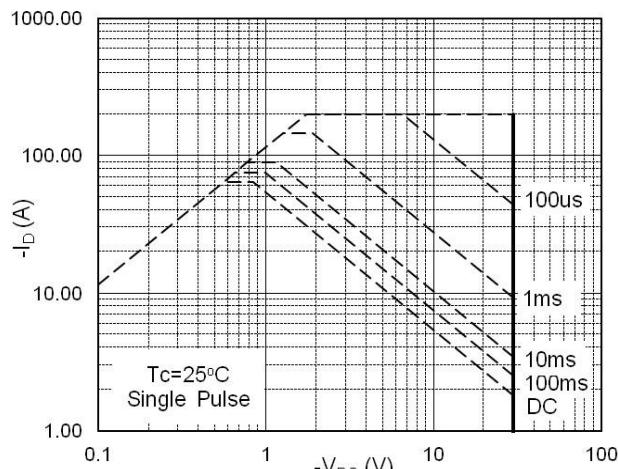


Fig.8 Safe Operating Area

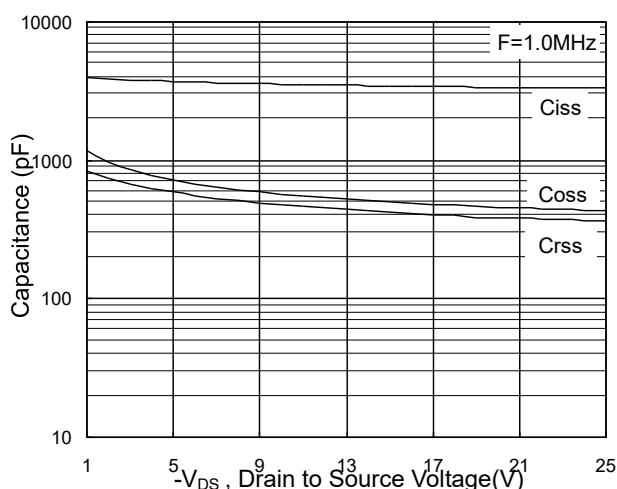


Fig.7 Capacitance

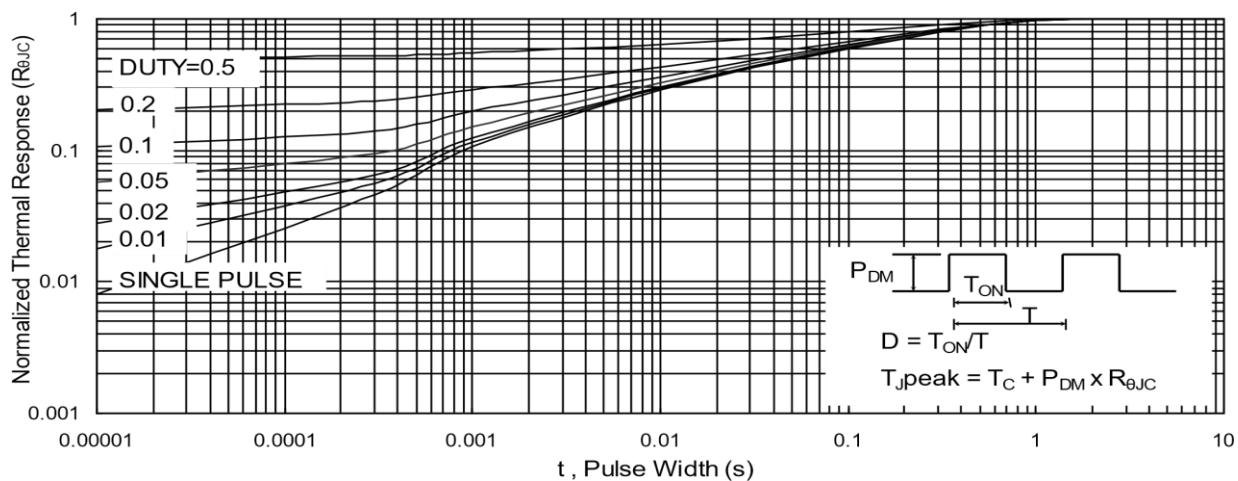


Fig.9 Normalized Maximum Transient Thermal Impedance

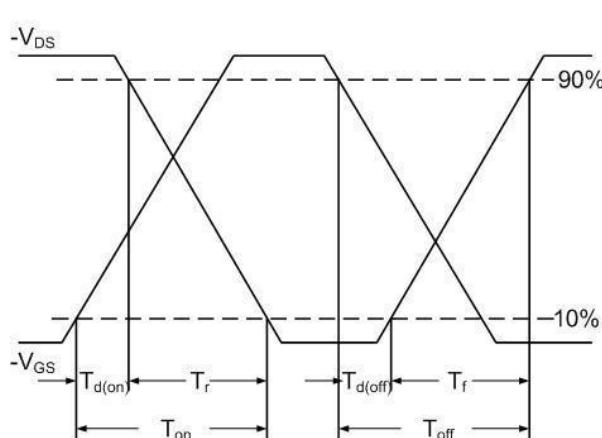


Fig.10 Switching Time Waveform

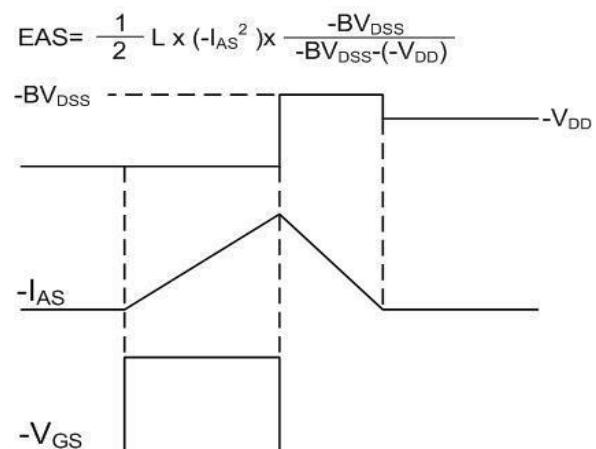
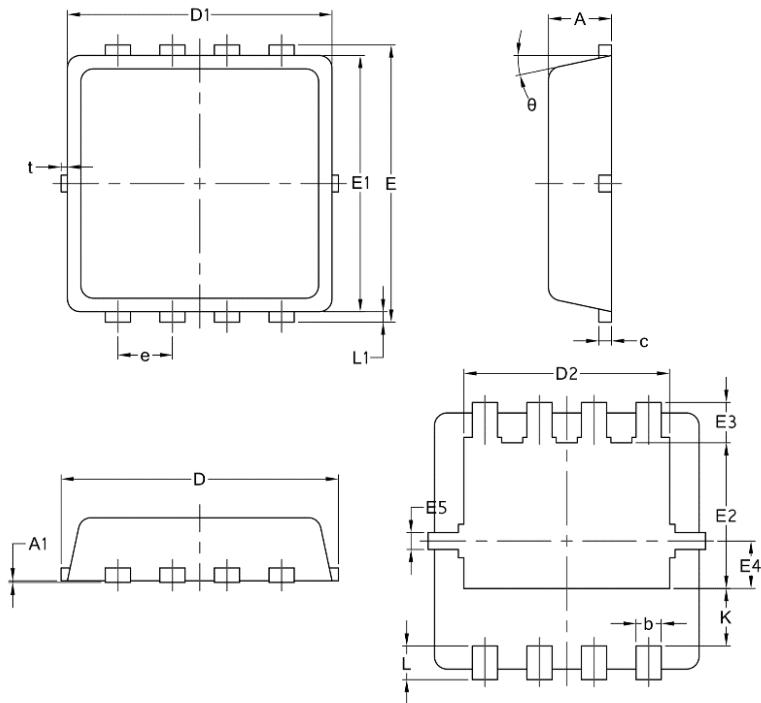


Fig.11 Unclamped Inductive Switching Waveform

-30V P-Channel Enhancement Mode MOSFET
Package Mechanical Data-DFN3*3-8L-JQ Single


Symbol	Common		
	mm		
	Mim	Nom	Max
A	0.70	0.75	0.85
A1	/	/	0.05
b	0.20	0.30	0.40
c	0.10	0.152	0.25
D	3.15	3.30	3.45
D1	3.00	3.15	3.25
D2	2.29	2.45	2.65
E	3.15	3.30	3.45
E1	2.90	3.05	3.20
E2	1.54	1.74	1.94
E3	0.28	0.48	0.65
E4	0.37	0.57	0.77
E5	0.10	0.20	0.30
e	0.60	0.65	0.70
K	0.59	0.69	0.89
L	0.30	0.40	0.50
L1	0.06	0.125	0.20
t	0	0.075	0.13
Φ	10	12	14